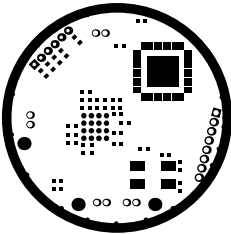
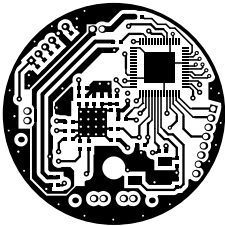


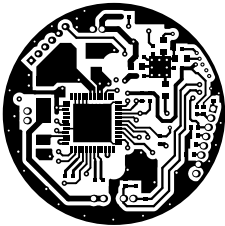
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/27/2013 12:49:21 PM	TEXAS INSTRUMENTS	



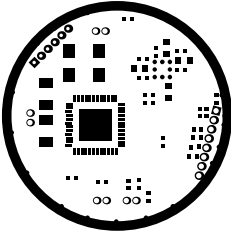
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/27/2013 12:49:21 PM	TEXAS INSTRUMENTS	



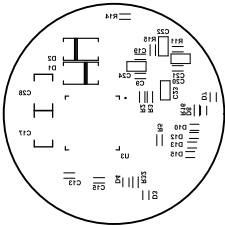
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/27/2013 12:49:22 PM	TEXAS INSTRUMENTS	



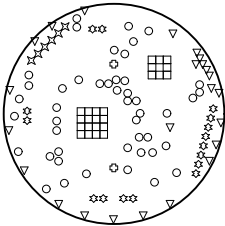
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/27/2013 12:49:22 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/27/2013 12:49:23 PM	TEXAS INSTRUMENTS	



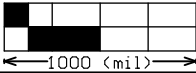
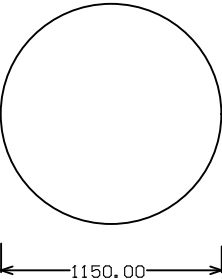
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/27/2013 12:49:23 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	24	10mil (0.254mm)	PTH	Round
□	24	11.811mil (0.3mm)	PTH	Round
○	46	12mil (0.305mm)	PTH	Round
⌘	6	18mil (0.457mm)	PTH	Round
☆	16	28mil (0.711mm)	PTH	Round
⊗	2	78.74mil (2mm)	PTH	Round
118 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/27/2013 12:49:24 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/27/2013 12:49:25 PM	TEXAS INSTRUMENTS	

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